

Surface Mountable PTC Resettable Fuse

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**RoHS
Compliant**



Specifications

Application	: All high-density boards.
Product Features	: Small surface mountable, solid state, faster time to trip than standard SMD devices, lower resistance than standard SMD devices.
Max. Voltage	: 6V to 60V.
Temperature Range	: -40°C to 85°C
Approval	: UL Approved

Electrical Characteristics (23°C)

Hold Current	Trip Current	Rated Voltage	Max. Current	Typical Power	Max. Time to trip		Resistance		Part Number
					Current	Time	R _{Min}	R _{1Max}	
I _H , A	I _T , A	V _{MAX} , V DC	I _{MAX} , A	P _D , W	Amperes	Seconds	Ω	Ω	
0.75	1.5	24	40	1	8	0.2	0.11	0.29	MC36218
0.75	1.5	33	40	1	8	0.2	0.11	0.4	MC36219
1.1	2.2	24	100	1	8	0.5	0.06	0.2	MC36225
1.5	3	12	100	1	8	0.5	0.04	0.11	MC36231
1.5	3	24	100	1	8	1.5	0.04	0.12	MC36232
1.6	3.2	16	100	1	8	1	0.03	0.1	MC36235
2	3.5	8	100	1	8	2	0.02	0.07	MC36238
2.6	5	13.2	100	1.3	8	5	0.015	0.05	MC36242
2.6	5	16	100	1.3	8	5	0.015	0.05	MC36243

I_H = Hold current-maximum current at which the device will not trip at 23°C still air.

I_T = Trip current-minimum current at which the device will always trip at 23°C still air.

V_{MAX} = Maximum voltage device can withstand without damage at its rated current (I maximum).

I_{MAX} = Maximum fault current device can withstand without damage at rated voltage (V maximum).

P_D = Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.

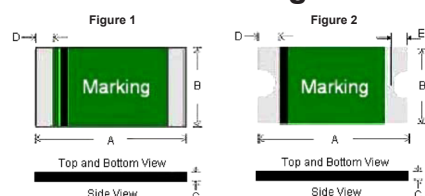
R_{Min} = Minimum device resistance at 23°C prior to tripping.

R_{1Max} = Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

Termination pad characteristics

Termination pad materials: Pure tin.

FSMD Product Diagram



A (mm)		B (mm)		C (mm)		D (mm)		E (mm)		Figure	Part Number
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
4.37	4.73	3.07	3.41	0.8	1.55	0.25	0.95	0.25	0.65	2	MC36218
4.37	4.73	3.07	3.41	0.8	1.55	0.25	0.95	0.25	0.65	2	MC36219

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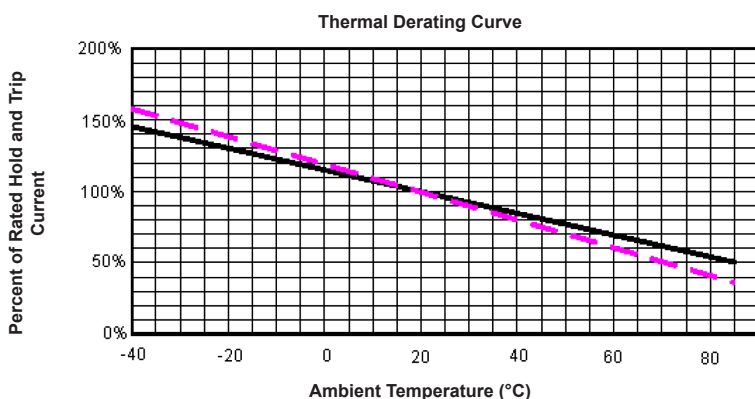
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A (mm)		B (mm)		C (mm)		D (mm)		E (mm)		Figure	Part Number
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
4.37	4.73	3.07	3.41	0.8	1.3	0.25	0.95	0.25	0.65	2	MC36225
4.37	4.73	3.07	3.41	0.6	1.1	0.25	0.95	0.25	0.65	2	MC36231
4.37	4.73	3.07	3.41	0.6	1.55	0.25	0.95	0.25	0.65	2	MC36232
4.37	4.73	3.07	3.41	0.6	1.35	0.25	0.95	0.25	0.65	2	MC36235
4.37	4.73	3.07	3.41	0.55	1.2	0.25	0.95	0.25	0.65	2	MC36238
4.37	4.73	3.07	3.41	0.8	1.55	0.25	0.95	0.25	0.65	2	MC36242
4.37	4.73	3.07	3.41	0.8	1.55	0.25	0.95	0.25	0.65	2	MC36243

Dimensions : Millimetres

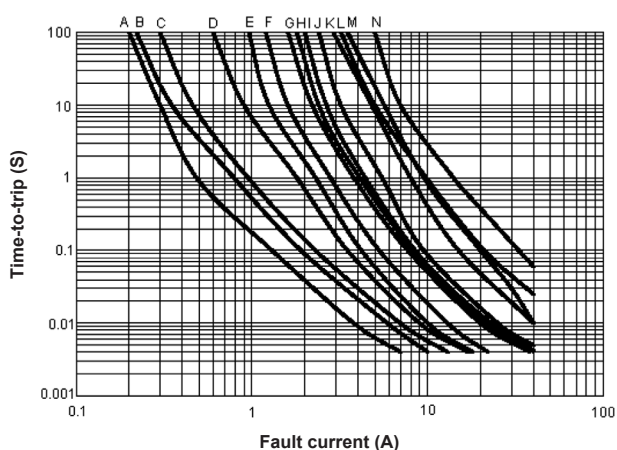
Thermal Derating Curve



A = MC36218, MC36219
MC36225, MC36231,
MC36232, MC36235,
MC36238, MC36242
MC36243

B = -

Typical Time-To-Trip at 23°C



A = -
D = -
F = MC36218, MC36219
G = MC36225
H = -
I = MC36231, MC36232
J = MC36235
M = -
K = MC36238
L = MC36242, MC36243

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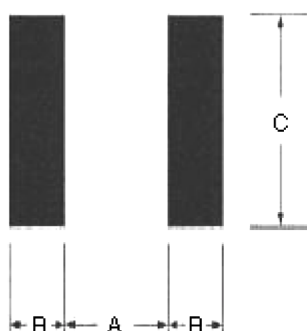
Material Specification

Terminal pad material : Pure tin.

Soldering characteristics : Meets EIA specification RS 186-9E, ANSI/J-std-002 category 3.

Pad Layouts Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each 1812 device.



Pad Dimensions

Device	A Nominal	B Nominal	C Nominal
All 1812 Series	3.45mm	1.78mm	3.5mm

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Ts maximum to TP)	3°C/second maximum
Preheat:	
Temperature Minimum (Ts minimum)	150°C
Temperature Maximum (Ts maximum)	200°C
Time (ts minimum to ts maximum)	60-180 seconds
Time maintained above:	
Temperature (TL)	217°C
Time (tL)	60-150 seconds
Peak/Classification Temperature (TP):	260°C
Time within 5°C of actual Peak:	
Temperature (tp)	20-40 seconds
Ramp-Down Rate:	6°C/second maximum
Time 25°C to Peak Temperature:	8 minutes maximum

Note 1: All temperatures refer to of the package, measured on the package body surface.

Solder reflow

Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.

1. Recommended max past thickness > 0.25mm.
2. Devices can be cleaned using standard methods and aqueous solvent.
3. Rework use standard industry practices.
4. Storage Environment : < 30°C/60%RH.

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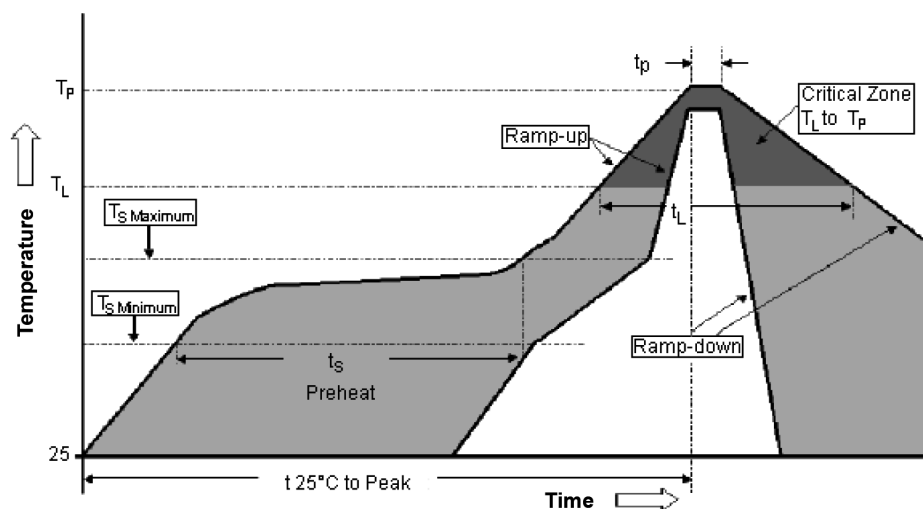
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Caution

1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
2. Devices are not designed to be wave soldered to the bottom side of the board.

Reflow Profile



Part Number Table

Description	TUV Approval	Part Number
Surface Mountable PTC Resettable Fuse	Yes	MC36218
		MC36219
		MC36225
		MC36231
		MC36232
	No	MC36235
		MC36238
		MC36242
		MC36243

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